

MODEL: HSS09-B20-P431 | DESCRIPTION: HEAT SINK

FEATURES

- TO-220 package
- solder pin
- aluminum alloy
- black anodized finish



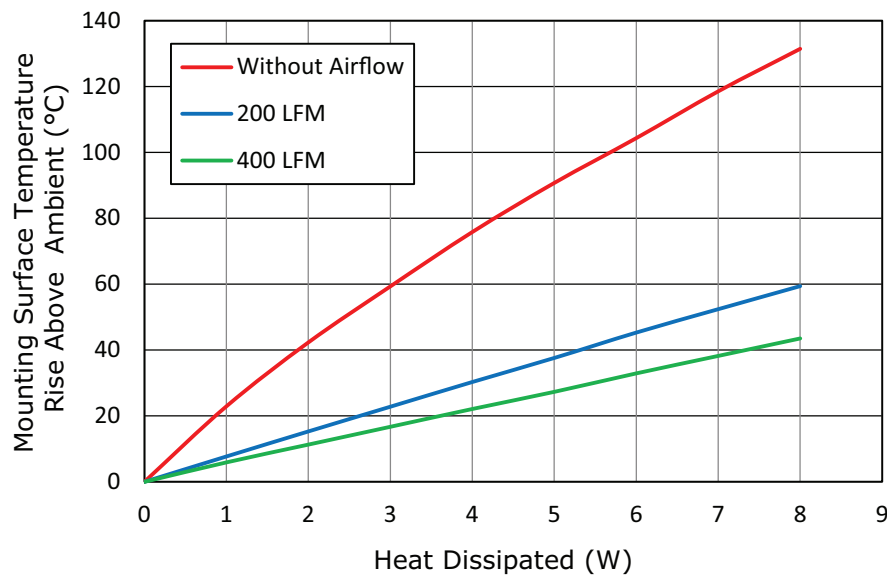
MODEL

MODEL	thermal resistance ¹				power dissipation ¹
	@ 75°C ΔT, nat conv (°C/W)	@ 1 W, nat conv (°C/W)	@ 1 W, 200 LFM (°C/W)	@ 1 W, 400 LFM (°C/W)	@ 75°C ΔT, nat conv (W)
HSS09-B20-P431	18.82	22.9	7.7	5.9	3.98

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) (°C)		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	22.9	7.7	5.9
2	42.3	15.3	11.3
3	59.3	22.8	16.7
4	75.8	30.3	22.1
5	90.7	37.6	27.3
6	104.3	45.3	32.9
7	118.5	52.6	38.2
8	131.4	59.4	43.5

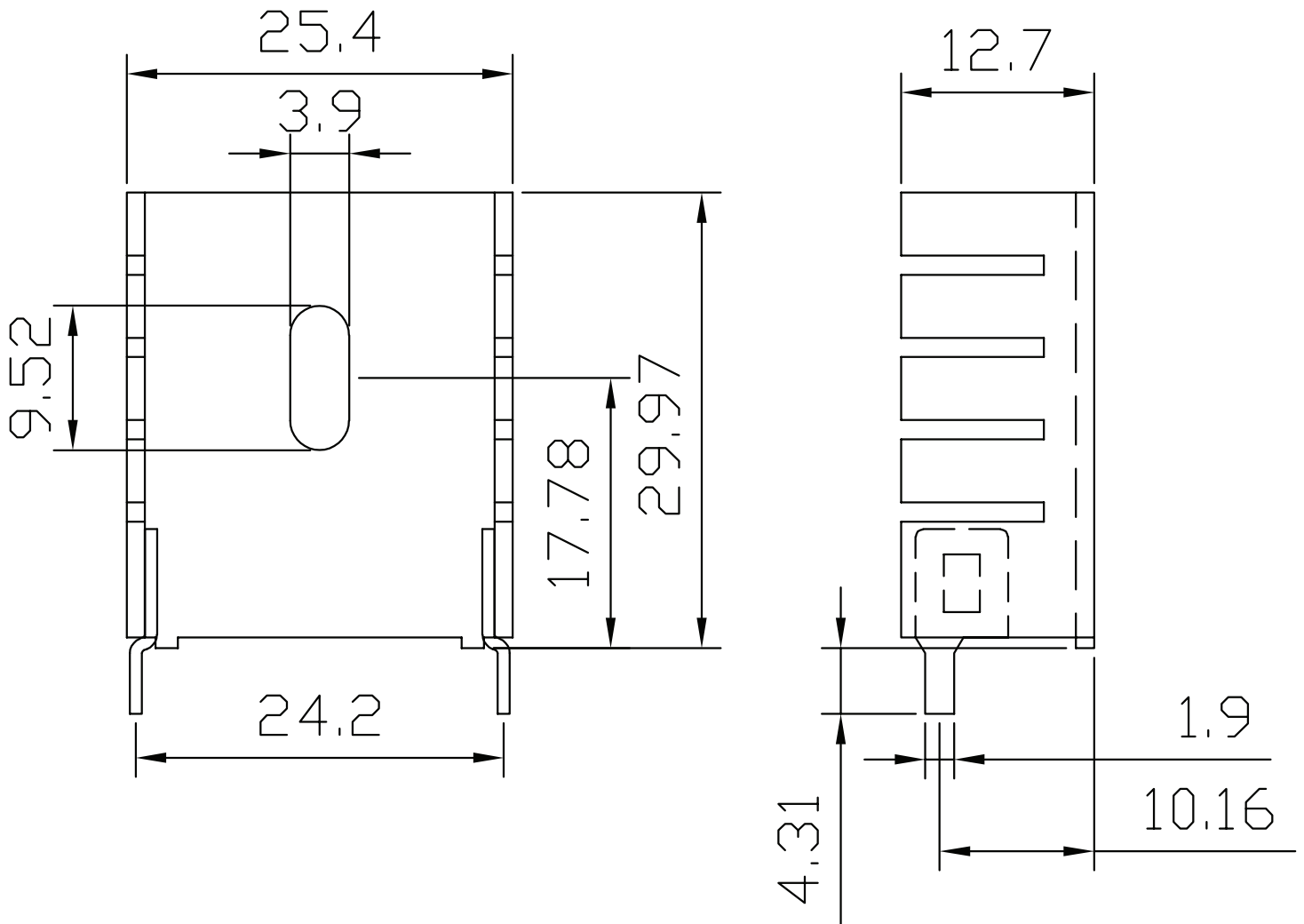


T_{hs}: "hot spot" temperature measured on the heatsink
 T_a: ambient temperature

MECHANICAL DRAWING

units: mm
tolerance: ± 0.38 mm

MATERIAL	AL 1050
FINISH	black anodized
THICKNESS	1.2 mm
PIN MATERIAL	brass
PIN PLATING	2~3 μ m tin
WEIGHT	5.0 g



REVISION HISTORY

rev.	description	date
1.0	initial release	06/25/2021

The revision history provided is for informational purposes only and is believed to be accurate.

CUI DEVICES

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